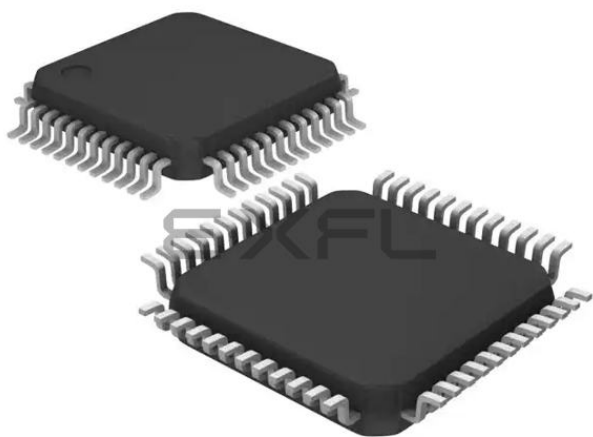




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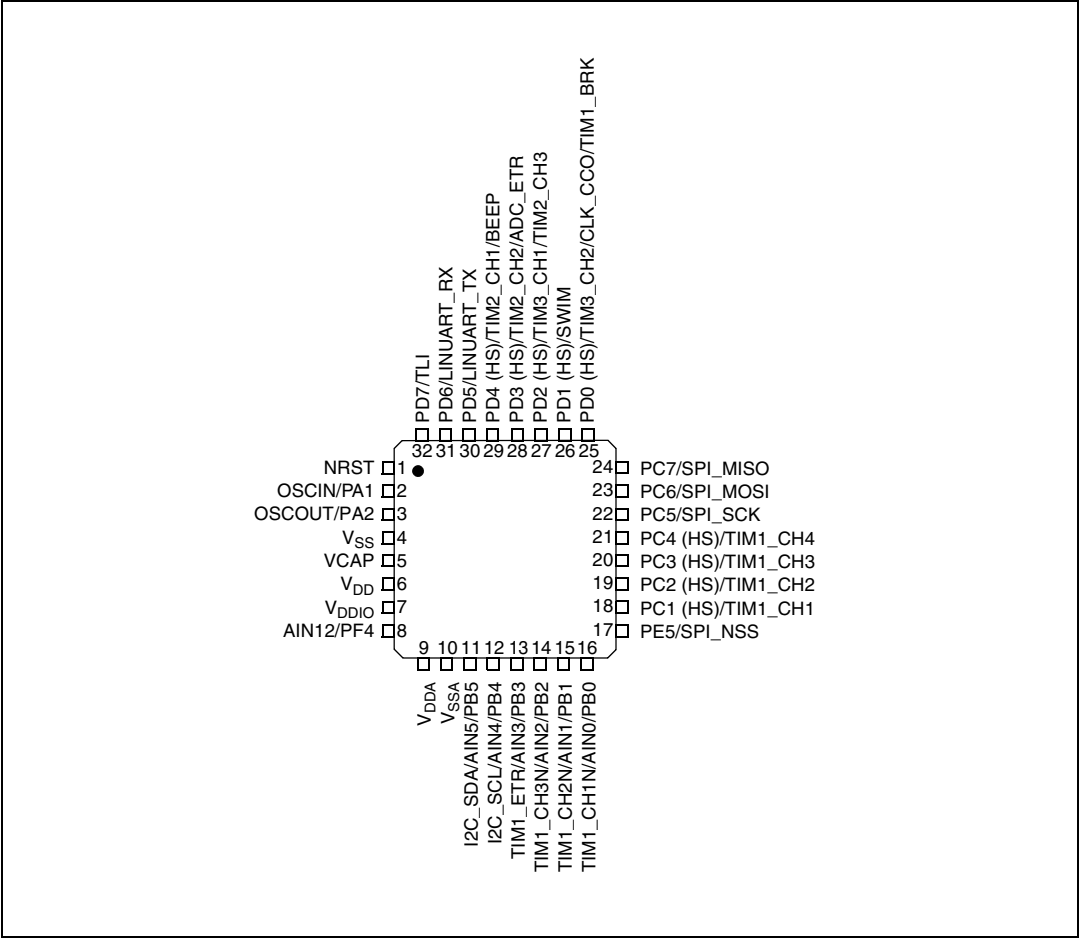
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Details

Product Status	Not For New Designs
Core Processor	STM8A
Core Size	8-Bit
Speed	24MHz
Connectivity	CANbus, I ² C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	38
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	1K x 8
RAM Size	6K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 5.5V
Data Converters	A/D 10x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	48-LQFP
Supplier Device Package	48-LQFP (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/stmicroelectronics/stm8af5268tcx

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Figure 6. STM8AF62xx LQFP/VFQFPN 32-pin pinout



1. HS stands for high sink capability.

Table 11. STM8AF526x/8x/Ax and STM8AF6269/8x/Ax pin description (continued)

Pin number					Pin name	Type	Input			Output				Main function (after reset)	Default alternate function	Alternate function after remap [option bit]
LQFP80	LQFP64	LQFP48	STM8AF62xx LQFP32/VQFPN32	STM8AF52x6 VQFPN32			Floating	Wpu	Ext. interrupt	High sink	Speed	OD	PP			
22	18	-	-	-	V _{REF+}	S	-	-	-	-	-	-	ADC positive reference voltage		-	
23	19	13	9	9	V _{DDA}	S	-	-	-	-	-	-	Analog power supply		-	
24	20	14	10	10	V _{SSA}	S	-	-	-	-	-	-	Analog ground		-	
25	21	-	-	-	V _{REF-}	S	-	-	-	-	-	-	ADC negative reference voltage		-	
26	22	-	-	-	PF0/AIN10	I/O	X	X	-	O1	X	X	Port F0	Analog input 10	-	
27	23	15	-	-	PB7/AIN7	I/O	X	X	X	-	O1	X	X	Port B7	Analog input 7	-
28	24	16	-	-	PB6/AIN6	I/O	X	X	X	-	O1	X	X	Port B6	Analog input 6	-
29	25	17	11	11	PB5/AIN5	I/O	X	X	X	-	O1	X	X	Port B5	Analog input 5	I ² C_SDA [AFR6]
30	26	18	12	12	PB4/AIN4	I/O	X	X	X	-	O1	X	X	Port B4	Analog input 4	I ² C_SCL [AFR6]
31	27	19	13	13	PB3/AIN3	I/O	X	X	X	-	O1	X	X	Port B3	Analog input 3	TIM1_ETR [AFR5]
32	28	20	14	14	PB2/AIN2	I/O	X	X	X	-	O1	X	X	Port B2	Analog input	TIM1_CH3N [AFR5]
33	29	21	15	15	PB1/AIN1	I/O	X	X	X	-	O1	X	X	Port B1	Analog input 1	TIM1_CH2N [AFR5]
34	30	22	16	16	PB0/AIN0	I/O	X	X	X	-	O1	X	X	Port B0	Analog input 0	TIM1_CH1N [AFR5]
35	-	-	-	-	PH4/TIM1_ETR	I/O	X	X	-	-	O1	X	X	Port H4	Timer 1 - trigger input	-
36	-	-	-	-	PH5/ TIM1_CH3N	I/O	X	X	-	-	O1	X	X	Port H5	Timer 1 - inverted channel 3	-
37	-	-	-	-	PH6/ TIM1_CH2N	I/O	X	X	-	-	O1	X	X	Port H6	Timer 1 - inverted channel 2	-

Table 11. STM8AF526x/8x/Ax and STM8AF6269/8x/Ax pin description (continued)

Pin number					Pin name	Type	Input				Output			Main function (after reset)	Default alternate function	Alternate function after remap [option bit]
LQFP80	LQFP64	LQFP48	STM8AF62xx LQFP32/VQFPN32	STM8AF52x6 VQFPN32			Floating	Wpu	Ext. interrupt	High sink	Speed	OD	PP			
38	-	-	-	-	PH7/ TIM1_CH1N	I/O	X	X	-	-	O1	X	X	Port H7	Timer 1 - inverted channel 2	-
39	31	23	-	-	PE7/AIN8	I/O	X	X	-	-	O1	X	X	Port E7	Analog input 8	-
40	32	24			PE6/AIN9	I/O	X	X	X	-	O1	X	X	Port E6	Analog input 9	-
41	33	25	17	17	PE5/SPI_NSS ⁽²⁾	I/O	X	X	X	-	O1	X	X	Port E5	SPI master/ slave select	-
42	-	-	-	-	PC0/ADC_ETR	I/O	X	X	X	-	O1	X	X	Port C0	ADC trigger input	-
43	34	26	18	18	PC1/TIM1_CH1	I/O	X	X	X	HS	O3	X	X	Port C1	Timer 1 - channel 1	-
44	35	27	19	19	PC2/TIM1_CH2	I/O	X	X	X	HS	O3	X	X	Port C2	Timer 1- channel 2	-
45	36	28	20	20	PC3/TIM1_CH3	I/O	X	X	X	HS	O3	X	X	Port C3	Timer 1 - channel 3	-
46	37	29	21	21	PC4/TIM1_CH4	I/O	X	X	X	HS	O3	X	X	Port C4	Timer 1 - channel 4	-
47	38	30	22	22	PC5/SPI_SCK ⁽²⁾	I/O	X	X	X	-	O3	X	X	Port C5	SPI clock	-
48	39	31	-	-	V _{SSIO_2}	S	-	-	-	-	-	-	-	I/O ground		-
49	40	32	-	-	V _{DDIO_2}	S	-	-	-	-	-	-	-	I/O power supply		-
50	41	33	23	-	PC6/SPI_MOSI ⁽²⁾	I/O	X	X	X	-	O3	X	X	Port C6	SPI master out/ slave in	-
51	42	34	24	-	PC7/SPI_MISO ⁽²⁾	I/O	X	X	X	-	O3	X	X	Port C7	SPI master in/ slave out	-
52	43	35	-	23	PG0/CAN_TX	I/O	X	X	-	-	O1	X	X	Port G0	CAN transmit	-
53	44	36	-	24	PG1/CAN_RX	I/O	X	X	-	-	O1	X	X	Port G1	CAN receive	-
54	45	-	-	-	PG2	I/O	X	X	-	-	O1	X	X	Port G2	-	-

Table 12. Memory model 128K

Flash program memory size	Flash program memory end address	RAM size	RAM end address	Stack roll-over address
128 K	0x00 27FFF	6 K	0x00 17FF	0x00 1400
64 K	0x00 17FFF			
32 K	0x00 0FFFF			

7.2 Register map

In this section the memory and register map of the devices covered by this datasheet is described. For a detailed description of the functionality of the registers, refer to STM8S series and STM8AF series 8-bit microcontrollers reference manual, RM0016.

Table 13. I/O port hardware register map

Address	Block	Register label	Register name	Reset status
0x00 5000	Port A	PA_ODR	Port A data output latch register	0x00
0x00 5001		PA_IDR	Port A input pin value register	0xXX ⁽¹⁾
0x00 5002		PA_DDR	Port A data direction register	0x00
0x00 5003		PA_CR1	Port A control register 1	0x00
0x00 5004		PA_CR2	Port A control register 2	0x00
0x00 5005	Port B	PB_ODR	Port B data output latch register	0x00
0x00 5006		PB_IDR	Port B input pin value register	0xXX ⁽¹⁾
0x00 5007		PB_DDR	Port B data direction register	0x00
0x00 5008		PB_CR1	Port B control register 1	0x00
0x00 5009		PB_CR2	Port B control register 2	0x00
0x00 500A	Port C	PC_ODR	Port C data output latch register	0x00
0x00 500B		PC_IDR	Port C input pin value register	0xXX ⁽¹⁾
0x00 500C		PC_DDR	Port C data direction register	0x00
0x00 500D		PC_CR1	Port C control register 1	0x00
0x00 500E		PC_CR2	Port C control register 2	0x00
0x00 500F	Port D	PD_ODR	Port D data output latch register	0x00
0x00 5010		PD_IDR	Port D input pin value register	0xXX ⁽¹⁾
0x00 5011		PD_DDR	Port D data direction register	0x00
0x00 5012		PD_CR1	Port D control register 1	0x02
0x00 5013		PD_CR2	Port D control register 2	0x00

Table 13. I/O port hardware register map (continued)

Address	Block	Register label	Register name	Reset status
0x00 5014	Port E	PE_ODR	Port E data output latch register	0x00
0x00 5015		PE_IDR	Port E input pin value register	0xXX ⁽¹⁾
0x00 5016		PE_DDR	Port E data direction register	0x00
0x00 5017		PE_CR1	Port E control register 1	0x00
0x00 5018		PE_CR2	Port E control register 2	0x00
0x00 5019	Port F	PF_ODR	Port F data output latch register	0x00
0x00 501A		PF_IDR	Port F input pin value register	0xXX ⁽¹⁾
0x00 501B		PF_DDR	Port F data direction register	0x00
0x00 501C		PF_CR1	Port F control register 1	0x00
0x00 501D		PF_CR2	Port F control register 2	0x00
0x00 501E	Port G	PG_ODR	Port G data output latch register	0x00
0x00 501F		PG_IDR	Port G input pin value register	0xXX ⁽¹⁾
0x00 5020		PG_DDR	Port G data direction register	0x00
0x00 5021		PG_CR1	Port G control register 1	0x00
0x00 5022		PG_CR2	Port G control register 2	0x00
0x00 5023	Port H	PH_ODR	Port H data output latch register	0x00
0x00 5024		PH_IDR	Port H input pin value register	0xXX ⁽¹⁾
0x00 5025		PH_DDR	Port H data direction register	0x00
0x00 5026		PH_CR1	Port H control register 1	0x00
0x00 5027		PH_CR2	Port H control register 2	0x00
0x00 5028	Port I	PI_ODR	Port I data output latch register	0x00
0x00 5029		PI_IDR	Port I input pin value register	0xXX ⁽¹⁾
0x00 502A		PI_DDR	Port I data direction register	0x00
0x00 502B		PI_CR1	Port I control register 1	0x00
0x00 502C		PI_CR2	Port I control register 2	0x00

1. Depends on the external circuitry.

Table 14. General hardware register map (continued)

Address	Block	Register label	Register name	Reset status
0x00 5320	TIM3	TIM3_CR1	TIM3 control register 1	0x00
0x00 5321		TIM3_IER	TIM3 interrupt enable register	0x00
0x00 5322		TIM3_SR1	TIM3 status register 1	0x00
0x00 5323		TIM3_SR2	TIM3 status register 2	0x00
0x00 5324		TIM3_EGR	TIM3 event generation register	0x00
0x00 5325		TIM3_CCMR1	TIM3 capture/compare mode register 1	0x00
0x00 5326		TIM3_CCMR2	TIM3 capture/compare mode register 2	0x00
0x00 5327		TIM3_CCER1	TIM3 capture/compare enable register 1	0x00
0x00 5328		TIM3_CNTRH	TIM3 counter high	0x00
0x00 5329		TIM3_CNTRL	TIM3 counter low	0x00
0x00 532A		TIM3_PSCR	TIM3 prescaler register	0x00
0x00 532B		TIM3_ARRH	TIM3 auto-reload register high	0xFF
0x00 532C		TIM3_ARRL	TIM3 auto-reload register low	0xFF
0x00 532D		TIM3_CCR1H	TIM3 capture/compare register 1 high	0x00
0x00 532E		TIM3_CCR1L	TIM3 capture/compare register 1 low	0x00
0x00 532F		TIM3_CCR2H	TIM3 capture/compare register 2 high	0x00
0x00 5330		TIM3_CCR2L	TIM3 capture/compare register 2 low	0x00
0x00 5331 to 0x00 533F	Reserved area (15 bytes)			
0x00 5340	TIM4	TIM4_CR1	TIM4 control register 1	0x00
0x00 5341		TIM4_IER	TIM4 interrupt enable register	0x00
0x00 5342		TIM4_SR	TIM4 status register	0x00
0x00 5343		TIM4_EGR	TIM4 event generation register	0x00
0x00 5344		TIM4_CNTR	TIM4 counter	0x00
0x00 5345		TIM4_PSCR	TIM4 prescaler register	0x00
0x00 5346		TIM4_ARR	TIM4 auto-reload register	0xFF
0x00 5347 to 0x00 53FF	Reserved area (185 bytes)			

Table 14. General hardware register map (continued)

Address	Block	Register label	Register name	Reset status
0x00 5400	ADC	ADC_CSR	ADC control/status register	0x00
0x00 5401		ADC_CR1	ADC configuration register 1	0x00
0x00 5402		ADC_CR2	ADC configuration register 2	0x00
0x00 5403		ADC_CR3	ADC configuration register 3	0x00
0x00 5404		ADC_DRH	ADC data register high	0xFF
0x00 5405		ADC_DRL	ADC data register low	0xFF
0x00 5406		ADC_TDRH	ADC Schmitt trigger disable register high	0x00
0x00 5407		ADC_TDRL	ADC Schmitt trigger disable register low	0x00
0x00 5408 to 0x00 541F	Reserved area (24 bytes)			
0x00 5420	beCAN	CAN_MCR	CAN master control register	0x02
0x00 5421		CAN_MSR	CAN master status register	0x02
0x00 5422		CAN_TSR	CAN transmit status register	0x00
0x00 5423		CAN_TPR	CAN transmit priority register	0x0C
0x00 5424		CAN_RFR	CAN receive FIFO register	0x00
0x00 5425		CAN_IER	CAN interrupt enable register	0x00
0x00 5426		CAN_DGR	CAN diagnosis register	0x0C
0x00 5427		CAN_FPSR	CAN page selection register	0x00
0x00 5428		CAN_P0	CAN paged register 0	0xFF ⁽³⁾
0x00 5429		CAN_P1	CAN paged register 1	0xFF ⁽³⁾
0x00 542A		CAN_P2	CAN paged register 2	0xFF ⁽³⁾
0x00 542B		CAN_P3	CAN paged register 3	0xFF ⁽³⁾
0x00 542C		CAN_P4	CAN paged register 4	0xFF ⁽³⁾
0x00 542D		CAN_P5	CAN paged register 5	0xFF ⁽³⁾
0x00 542E		CAN_P6	CAN paged register 6	0xFF ⁽³⁾
0x00 542F		CAN_P7	CAN paged register 7	0xFF ⁽³⁾
0x00 5430		CAN_P8	CAN paged register 8	0xFF ⁽³⁾
0x00 5431		CAN_P9	CAN paged register 9	0xFF ⁽³⁾
0x00 5432		CAN_PA	CAN paged register A	0xFF ⁽³⁾
0x00 5433		CAN_PB	CAN paged register B	0xFF ⁽³⁾
0x00 5434		CAN_PC	CAN paged register C	0xFF ⁽³⁾
0x00 5435		CAN_PD	CAN paged register D	0xFF ⁽³⁾
0x00 5436		CAN_PE	CAN paged register E	0xFF ⁽³⁾

Table 14. General hardware register map (continued)

Address	Block	Register label	Register name	Reset status
0x00 5437	beCAN	CAN_PF	CAN paged register F	0xXX ⁽³⁾
0x00 5438 to 0x00 57FF	Reserved area (968 bytes)			

1. Depends on the previous reset source.
2. Write only register.
3. If the bootloader is enabled, it is initialized to 0x00.

Table 15. CPU/SWIM/debug module/interrupt controller registers

Address	Block	Register label	Register name	Reset status
0x00 7F00	CPU ⁽¹⁾	A	Accumulator	0x00
0x00 7F01		PCE	Program counter extended	0x00
0x00 7F02		PCH	Program counter high	0x80
0x00 7F03		PCL	Program counter low	0x00
0x00 7F04		XH	X index register high	0x00
0x00 7F05		XL	X index register low	0x00
0x00 7F06		YH	Y index register high	0x00
0x00 7F07		YL	Y index register low	0x00
0x00 7F08		SPH	Stack pointer high	0x17 ⁽²⁾
0x00 7F09		SPL	Stack pointer low	0xFF
0x00 7F0A		CC	Condition code register	0x28
0x00 7F0B to 0x00 7F5F	Reserved area (85 bytes)			
0x00 7F60	CPU	CFG_GCR	Global configuration register	0x00
0x00 7F70	ITC	ITC_SPR1	Interrupt software priority register 1	0xFF
0x00 7F71		ITC_SPR2	Interrupt software priority register 2	0xFF
0x00 7F72		ITC_SPR3	Interrupt software priority register 3	0xFF
0x00 7F73		ITC_SPR4	Interrupt software priority register 4	0xFF
0x00 7F74		ITC_SPR5	Interrupt software priority register 5	0xFF
0x00 7F75		ITC_SPR6	Interrupt software priority register 6	0xFF
0x00 7F76		ITC_SPR7	Interrupt software priority register 7	0xFF
0x00 7F77		ITC_SPR8	Interrupt software priority register 8	0xFF
0x00 7F78 to 0x00 7F79	Reserved area (2 bytes)			
0x00 7F80	SWIM	SWIM_CSR	SWIM control status register	0x00

Table 19. Option byte description

Option byte no.	Description
OPT0	ROP[7:0]: Memory readout protection (ROP) 0xAA: Enable readout protection (write access via SWIM protocol) <i>Note: Refer to STM8S series and STM8AF series 8-bit microcontrollers reference manual (RM0016) section on Flash/EEPROM memory readout protection for details.</i>
OPT1	UBC[7:0]: User boot code area 0x00: No UBC, no write-protection 0x01: Page 0 to 1 defined as UBC, memory write-protected 0x02: Page 0 to 3 defined as UBC, memory write-protected 0x03 to 0xFF: Pages 4 to 255 defined as UBC, memory write-protected <i>Note: Refer to STM8S series and STM8AF series 8-bit microcontrollers reference manual (RM0016) section on Flash/EEPROM write protection for more details.</i>
OPT2	AFR7: Alternate function remapping option 7 0: Port D4 alternate function = TIM2_CH1 1: Port D4 alternate function = BEEP AFR6: Alternate function remapping option 6 0: Port B5 alternate function = AIN5, port B4 alternate function = AIN4 1: Port B5 alternate function = I ² C_SDA, port B4 alternate function = I ² C_SCL. AFR5: Alternate function remapping option 5 0: Port B3 alternate function = AIN3, port B2 alternate function = AIN2, port B1 alternate function = AIN1, port B0 alternate function = AIN0. 1: Port B3 alternate function = TIM1_ETR, port B2 alternate function = TIM1_CH3N, port B1 alternate function = TIM1_CH2N, port B0 alternate function = TIM1_CH1N. AFR4: Alternate function remapping option 4 0: Port D7 alternate function = TLI 1: Reserved AFR3: Alternate function remapping option 3 0: Port D0 alternate function = TIM3_CH2 1: Port D0 alternate function = TIM1_BKIN AFR2: Alternate function remapping option 2 0: Port D0 alternate function = TIM3_CH2 1: Port D0 alternate function = CLK_CCO <i>Note: AFR2 option has priority over AFR3 if both are activated</i> AFR1: Alternate function remapping option 1 0: Port A3 alternate function = TIM2_CH3, port D2 alternate function TIM3_CH1. 1: Port A3 alternate function = TIM3_CH1, port D2 alternate function TIM2_CH3. AFR0: Alternate function remapping option 0 0: Port D3 alternate function = TIM2_CH2 1: Port D3 alternate function = ADC_ETR

10.3.4 Internal clock sources and timing characteristics

Subject to general operating conditions for V_{DD} and T_A .

High-speed internal RC oscillator (HSI)

Table 33. HSI oscillator characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
f_{HSI}	Frequency	-	-	16	-	MHz
ACC_{HS}	HSI oscillator user trimming accuracy	Trimmed by the application for any V_{DD} and T_A conditions	-1	-	1	%
	HSI oscillator accuracy (factory calibrated)	$V_{DD} = 3.0\text{ V} \leq V_{DD} \leq 5.5\text{ V}$, $-40\text{ }^{\circ}\text{C} \leq T_A \leq 150\text{ }^{\circ}\text{C}$	-5	-	5	
$t_{su(HSI)}$	HSI oscillator wakeup time	-	-	-	2 ⁽¹⁾	μs

1. Guaranteed by characterization results, not tested in production.

Figure 21. Typical HSI frequency vs V_{DD}

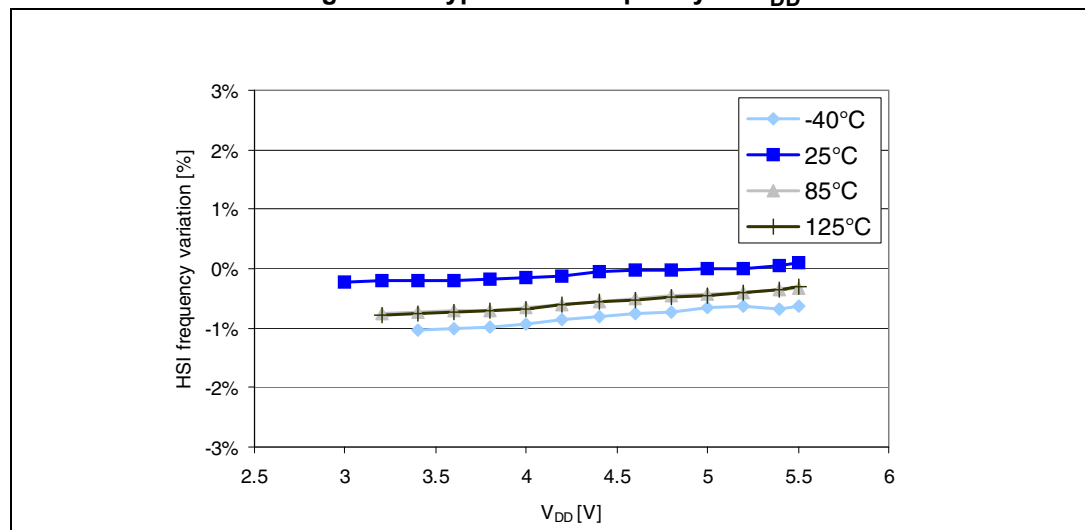
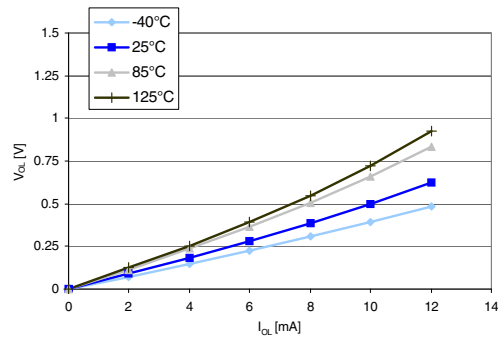
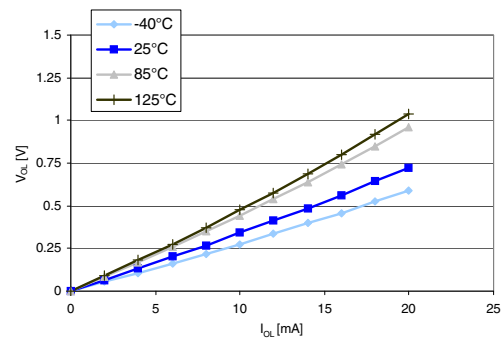
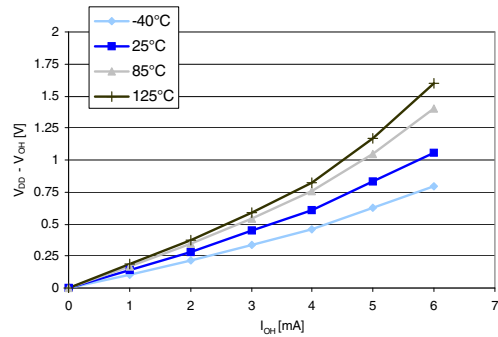
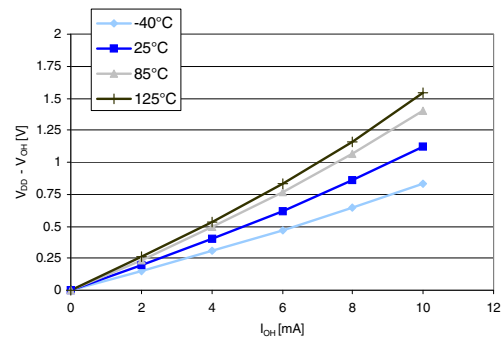
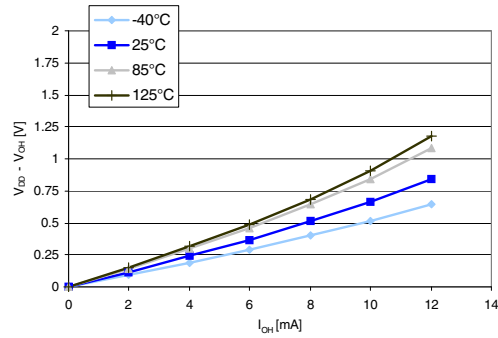
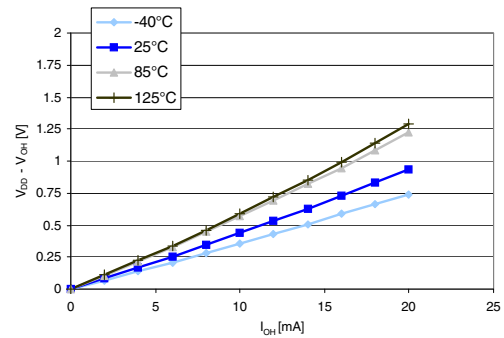


Figure 30. Typ. V_{OL} @ $V_{DD} = 3.3$ V (high sink ports)**Figure 31. Typ. V_{OL} @ $V_{DD} = 5.0$ V (high sink ports)****Figure 32. Typ. $V_{DD} - V_{OH}$ @ $V_{DD} = 3.3$ V (standard ports)****Figure 33. Typ. $V_{DD} - V_{OH}$ @ $V_{DD} = 5.0$ V (standard ports)****Figure 34. Typ. $V_{DD} - V_{OH}$ @ $V_{DD} = 3.3$ V (high sink ports)****Figure 35. Typ. $V_{DD} - V_{OH}$ @ $V_{DD} = 5.0$ V (high sink ports)**

10.3.11 10-bit ADC characteristics

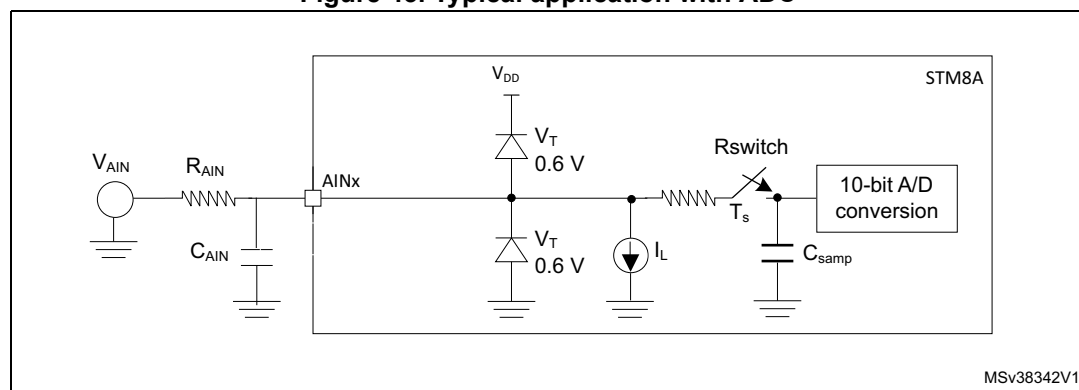
Subject to general operating conditions for V_{DDA} , f_{MASTER} and T_A unless otherwise specified.

Table 43. ADC characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
f_{ADC}	ADC clock frequency	-	111 kHz	-	4 MHz	kHz/MHz
V_{DDA}	Analog supply	-	3	-	5.5	V
V_{REF+}	Positive reference voltage	-	2.75	-	V_{DDA}	
V_{REF-}	Negative reference voltage	-	V_{SSA}	-	0.5	
V_{AIN}	Conversion voltage range ⁽¹⁾	-	V_{SSA}	-	V_{DDA}	
		Devices with external V_{REF+}/V_{REF-} pins	V_{REF-}	-	V_{REF+}	
C_{smp}	Internal sample and hold capacitor	-	-	-	3	pF
$t_S^{(1)}$	Sampling time ($3 \times 1/f_{ADC}$)	$f_{ADC} = 2$ MHz	-	1.5	-	μs
		$f_{ADC} = 4$ MHz	-	0.75	-	
t_{STAB}	Wakeup time from standby	$f_{ADC} = 2$ MHz	-	7	-	
		$f_{ADC} = 4$ MHz	-	3.5	-	
t_{CONV}	Total conversion time including sampling time ($14 \times 1/f_{ADC}$)	$f_{ADC} = 2$ MHz	-	7	-	
		$f_{ADC} = 4$ MHz	-	3.5	-	
R_{switch}	Equivalent switch resistance	-	-	-	30	k Ω

1. During the sample time, the sampling capacitance, C_{smp} (3 pF typ), can be charged/discharged by the external source. The internal resistance of the analog source must allow the capacitance to reach its final voltage level within t_S . After the end of the sample time t_S , changes of the analog input voltage have no effect on the conversion result.

Figure 43. Typical application with ADC



1. Legend: R_{AIN} = external resistance, C_{AIN} = capacitors, C_{smp} = internal sample and hold capacitor.

Electromagnetic interference (EMI)

Emission tests conform to the IEC 61967-2 standard for test software, board layout and pin loading.

Table 46. EMI data

Symbol	Parameter	Conditions					Unit
		General conditions	Monitored frequency band	Max f _{CPU} ⁽¹⁾			
				8 MHz	16 MHz	24 MHz	
S _{EMI}	Peak level	V _{DD} = 5 V, T _A = 25 °C, LQFP80 package conforming to IEC 61967-2	0.1 MHz to 30 MHz	15	17	22	dBμV
			30 MHz to 130 MHz	18	22	16	
			130 MHz to 1 GHz	-1	3	5	
	EMI level		-	2	2.5	2.5	

1. Guaranteed by characterization results, not tested in production.

Absolute maximum ratings (electrical sensitivity)

Based on two different tests (ESD and LU) using specific measurement methods, the product is stressed to determine its performance in terms of electrical sensitivity. For more details, refer to the application note AN1181.

Electrostatic discharge (ESD)

Electrostatic discharges (3 positive then 3 negative pulses separated by 1 second) are applied to the pins of each sample according to each pin combination. The sample size depends on the number of supply pins in the device (3 parts*(n+1) supply pin). This test conforms to the JESD22-A114A/A115A standard. For more details, refer to the application note AN1181.

Table 47. ESD absolute maximum ratings

Symbol	Ratings	Conditions	Class	Maximum value ⁽¹⁾	Unit
$V_{ESD(HBM)}$	Electrostatic discharge voltage (human body model)	$T_A = 25\text{ }^{\circ}\text{C}$, conforming to JESD22-A114	3A	4000	V
$V_{ESD(CDM)}$	Electrostatic discharge voltage (charge device model)	$T_A = 25\text{ }^{\circ}\text{C}$, conforming to JESD22-C101	3	500	
$V_{ESD(MM)}$	Electrostatic discharge voltage (charge device model)	$T_A = 25\text{ }^{\circ}\text{C}$, conforming to JESD22-A115	B	200	

1. Guaranteed by characterization results, not tested in production

**Table 49. LQFP80 - 80-pin, 14 x 14 mm low-profile quad flat package
mechanical data⁽¹⁾**

Symbol	millimeters			inches		
	Min	Typ	Max	Min	Typ	Max
A	-	-	1.600	-	-	0.0630
A1	0.050	-	0.150	0.0020	-	0.0059
A2	1.350	1.400	1.450	0.0531	0.0551	0.0571
b	0.220	0.320	0.380	0.0087	0.0126	0.0150
c	0.090	-	0.200	0.0035	-	0.0079
D	15.800	16.000	16.200	0.6220	0.6299	0.6378
D1	13.800	14.000	14.200	0.5433	0.5512	0.5591
D3	-	12.350	-	-	0.4862	-
E	15.800	16.000	16.200	0.6220	0.6299	0.6378
E1	13.800	14.000	14.200	0.5433	0.5512	0.5591
E3	-	12.350	-	-	0.4862	-
e	-	0.650	-	-	0.0256	-
L	0.450	0.600	0.750	0.0177	0.0236	0.0295
L1	-	1.000	-	-	0.0394	-
k	0°	3.5°	7°	0°	3.5°	7°
ccc	-	-	0.100	-	-	0.0039

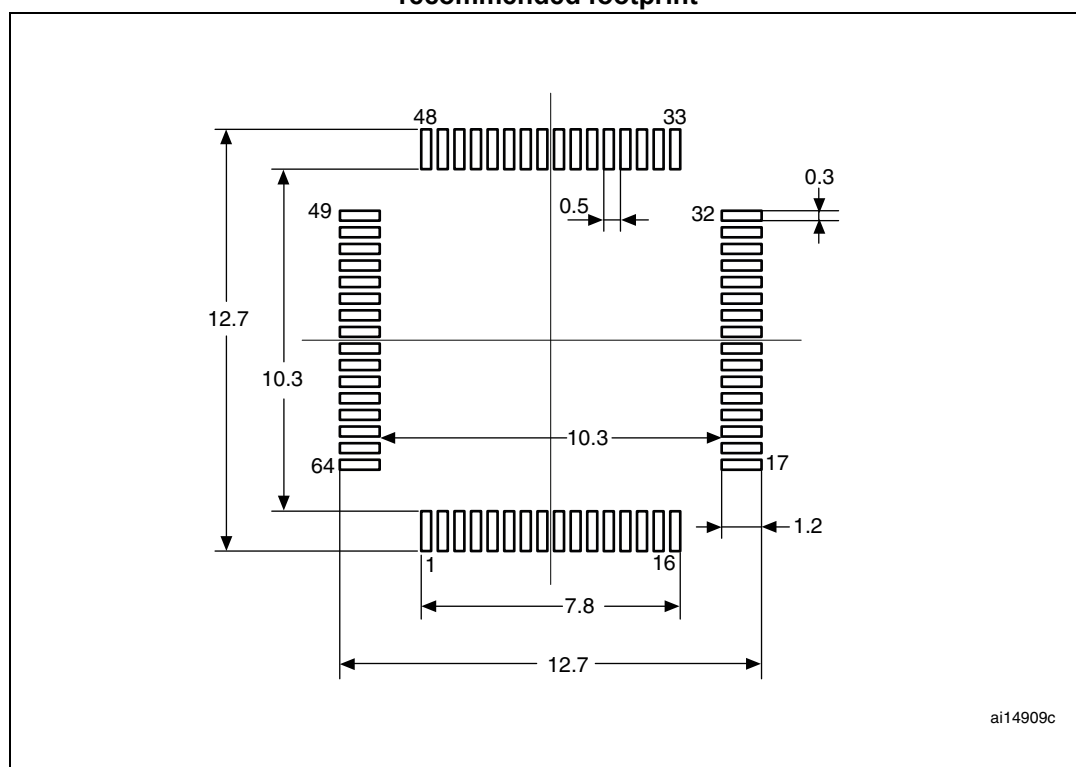
1. Values in inches are converted from mm and rounded to 4 decimal digits.

Table 50. LQFP64 - 64-pin, 10 x 10 mm low-profile quad flat package mechanical data (continued)

Symbol	millimeters			inches ⁽¹⁾		
	Min	Typ	Max	Min	Typ	Max
E3	-	7.500	-	-	0.2953	-
e	-	0.500	-	-	0.0197	-
K	0°	3.5°	7°	0°	3.5°	7°
L	0.450	0.600	0.750	0.0177	0.0236	0.0295
L1	-	1.000	-	-	0.0394	-
ccc	-	-	0.080	-	-	0.0031

1. Values in inches are converted from mm and rounded to 4 decimal digits.

Figure 49. LQFP64 - 64-pin, 10 x 10 mm low-profile quad flat package recommended footprint



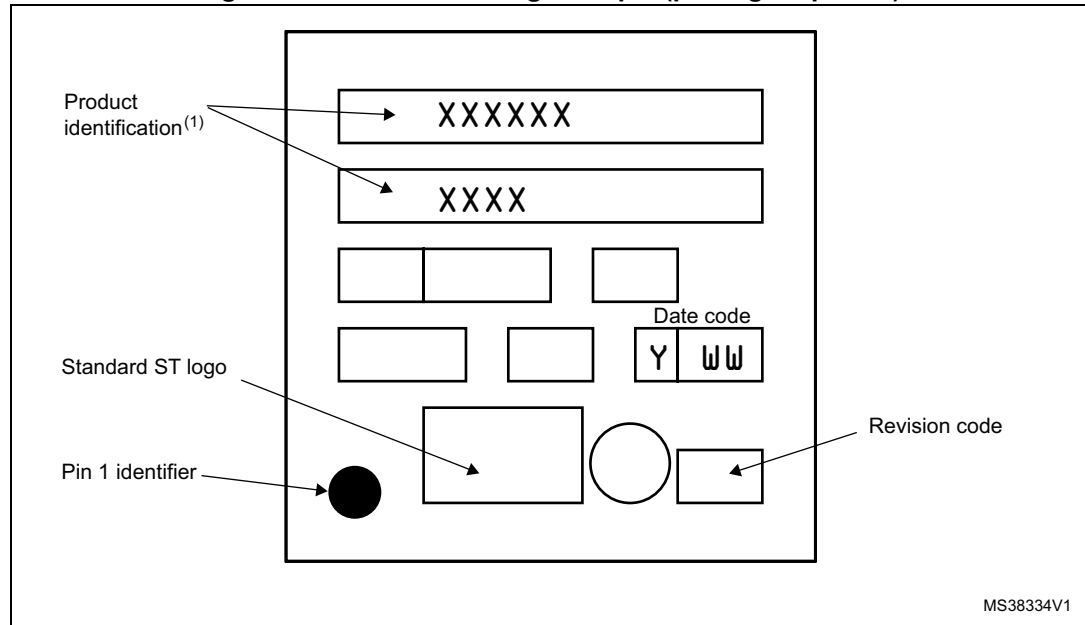
1. Dimensions are expressed in millimeters.

Device marking

The following figure gives an example of topside marking orientation versus pin 1 identifier location.

Other optional marking or inset/upset marks, which identify the parts throughout supply chain operations, are not indicated below.

Figure 50. LQFP64 marking example (package top view)



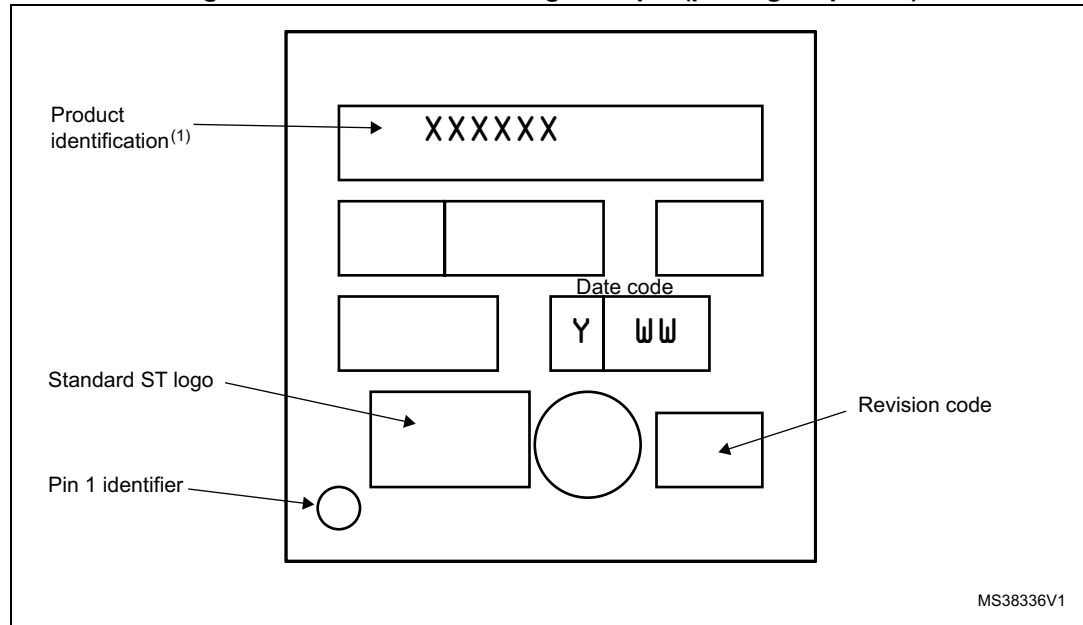
1. Parts marked as "ES", "E" or accompanied by an Engineering Sample notification letter are not yet qualified and therefore not approved for use in production. ST is not responsible for any consequences resulting from such use. In no event will ST be liable for the customer using any of these engineering samples in production. ST's quality department must be contacted to run a qualification activity prior to any decision to use these engineering samples.

Device marking

The following figure gives an example of topside marking orientation versus pin 1 identifier location.

Other optional marking or inset/upset marks, which identify the parts throughout supply chain operations, are not indicated below.

Figure 59. VFQFPN32 marking example (package top view)



1. Parts marked as "ES", "E" or accompanied by an Engineering Sample notification letter are not yet qualified and therefore not approved for use in production. ST is not responsible for any consequences resulting from such use. In no event will ST be liable for the customer using any of these engineering samples in production. ST's quality department must be contacted to run a qualification activity prior to any decision to use these engineering samples.

13.3 Programming tools

During the development cycle, STice provides in-circuit programming of the STM8A Flash microcontroller on the application board via the SWIM protocol. Additional tools are to include a low-cost in-circuit programmer as well as ST socket boards, which provide dedicated programming platforms with sockets for programming the STM8A.

For production environments, programmers will include a complete range of gang and automated programming solutions from third-party tool developers already supplying programmers for the STM8 family.

Table 55. Document revision history (continued)

Date	Revision	Changes
16-Sep-2008	3	Replaced the salestype 'STM8H61xx' with 'STM8AH61xx' on the first page. Added 'part numbers' to heading rows of Table 1: Device summary. Updated the 80-pin package silhouette on cover page in line with POA 0062342-revD. Table 18: Renamed 'TMU key registers 0-7 [7:0]' as 'TMU key registers 1-8 [7:0]' Section 9: Updated introductory text concerning option bytes which do not need to be saved in a complementary form. Table 18: Renamed the option bits 'TMU[0:3]', 'NTMU[0:3]', and 'TMU_KEY 0-7 [7:0]' as 'TMU[3:0]', 'NTMU[3:0]', and 'TMU_KEY 1-8 [7:0]' respectively. Table 21: Updated values of option byte 5 (HSECNT[7:0]); inverted the description of option byte 6 (TMU[3:0]); renamed option bytes 8 to 15 'TMU_KEY 0-7 [7:0]', as 'TMU_KEY 1-8 [7:0]'. Updated 80-pin package information in line with POA 0062342-revD in Figure 45 and Table 53.
01-Jul-2009	4	Added 'STM8AH61xx' and 'STM8AH51xx' to document header. Updated : Features on page 1 (memories, timers, operating temperature, ADC and I/Os). Updated Table 1: Device summary Updated Kbyte value of program memory in Section: Introduction Changed the first two lines from the top in Section: Description. Updated Figure 1: STM8AF526x/8x/Ax and STM8AF6269/8x/Ax block diagram Updated Section 5: Product overview In Figure 5: LQFP 48-pin pinout, added USART function to pins 10, 11, and 12; added CAN Tx and CAN Rx functions to pins 35 and 36 respectively. Section 6: Pinouts and pin description: deleted the text below the Table 10: Legend/abbreviation for the pin description table Table 11: STM8AF526x/8x/Ax and STM8AF6269/8x/Ax pin description: 68th, 69th pin (LQFP80): replaced X with a dash for PP output and Added a table footnote. Updated Figure 8: Register and memory map. Table 12: Memory model 128K: updated footnote Deleted the Table: Stack and RAM partitioning Table 17: STM8A interrupt table: Updated priorities 13, 15, 17, 20 and 24 and changed table footnote Updated Section 7: Memory and register map Updated Table: Data memory, Table: I/O static characteristics, and Table 39: NRST pin characteristics. Section 10.1.1: Minimum and maximum values: added ambient temperature $T_A = -40\text{ }^{\circ}\text{C}$ Updated Table 20: Voltage characteristics. Updated Table 21: Current characteristics. Updated Table 22: Thermal characteristics. Updated Table 24: General operating conditions.